

### 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

## Notification# 20180521001 Datasheet for TPS61500 Information Only

**Date:** May 31, 2018 **To:** Newark/Farnell PCN

#### Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

# Information Only Attachments

#### **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

**DEVICE**TPS61500PWP
TPS61500PWPR

**CUSTOMER PART NUMBER** 

null null

Technical details of this Product Change follow on the next page(s).

Title: Datasheet for TPS61500  Customer Contact: PCN Manager  Dept: Quality Services  Change Type:  □ Assembly Site □ Assembly Process □ Mafer Bump Site □ Assembly Materials □ Assembly Materials □ Part number change □ Wafer Bump Material □ Assembly Materials □ Part number change □ Wafer Bump Material □ Mafer Bump Process □ Wafer Bump Process □ Wafer Bump Process □ Wafer Bump Process □ Wafer Fab Materials □ Wafer Bump Material □ Wafer Bump Paperion □ Wafer Bump Paperion □ Wafer Bump Paperion □ Wafer B	Title: Datasheet for TPS61500  Customer Contact: PCN Manager  Change Type:  Assembly Site Design Assembly Process Data Sheet Assembly Materials Part number change Mechanical Specification Test Site Packing/Shipping/Labeling Test Process  Notification Details  Description of Change:	Dep	Wafer Bump Site Wafer Bump Material Wafer Bump Process Wafer Fab Site Wafer Fab Materials				
Assembly Site	Change Type:  ☐ Assembly Site ☐ Design ☐ Assembly Process ☐ Data Sheet ☐ Assembly Materials ☐ Part number change ☐ Mechanical Specification ☐ Test Site ☐ Packing/Shipping/Labeling ☐ Test Process  Notification Details  Description of Change:		Wafer Bump Site Wafer Bump Material Wafer Bump Process Wafer Fab Site Wafer Fab Materials				
Assembly Site	□ Assembly Site       □ Design         □ Assembly Process       □ Data Sheet         □ Assembly Materials       □ Part number change         □ Mechanical Specification       □ Test Site         □ Packing/Shipping/Labeling       □ Test Process         Notification Details         Description of Change:		Wafer Bump Material Wafer Bump Process Wafer Fab Site Wafer Fab Materials				
Assembly Process Assembly Materials Wafer Fab Site Wafer Fab Site Wafer Fab Materials Wafer Fab Process  Notification Details  Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.  TPS61500  Changes from Revision D (June 2017) to Revision E Page  Changed ground symbol of R3 change from PGND to AGND in Typical Application Circuit 1 Changed ground symbol of R3 change from PGND to AGND in Figure 7 12 Changed ground symbol of R3 change from PGND to AGND in Figure 11 17  TEXAS TPS61500  SLVS893D—DECEMBER 2008—REVISED JUNE 2017  Changes from Revision C (March 2015) to Revision D Page  Changed "Analog and PVM dimming frequency" to "PVM dimming frequency" in ROC table; add separate row for "Analog dimming frequency" Added sentence at end of Analog Dimming Method 11  The datasheet number will be changing. Device Family Changes may be reviewed at the datasheet links provided.	□ Assembly Process       □ Data Sheet         □ Assembly Materials       □ Part number change         □ Mechanical Specification       □ Test Site         □ Packing/Shipping/Labeling       □ Test Process         Notification Details         Description of Change:		Wafer Bump Material Wafer Bump Process Wafer Fab Site Wafer Fab Materials				
Assembly Materials  Mechanical Specification  Mechanical Specification  Test Site  Wafer Fab Site  Wafer Fab Materials  Wafer Fab Materials  Wafer Fab Materials  Wafer Fab Materials  Wafer Fab Process  Notification Details  Description of Change:  Texas Instruments Incorporated is announcing an information only notification.  The product datasheet(s) is being updated as summarized below.  The following change history provides further details.  Texas  Instruments  Changes from Revision D (June 2017) to Revision E  Changed ground symbol of R3 change from PGND to AGND in Typical Application Circuit  Changed ground symbol of R3 change from PGND to AGND in Figure 7  Changed ground symbol of R3 change from PGND to AGND in Figure 11  Changed ground symbol of R3 change from PGND to AGND in Figure 11  Changed ground symbol of R3 change from PGND to AGND in Figure 11  Texas  Tesas	Assembly Materials  Mechanical Specification  Packing/Shipping/Labeling  Notification Details  Description of Change:		Wafer Bump Process Wafer Fab Site Wafer Fab Materials				
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Packing/Shipping/Labeling   Test Process   Wafer Fab Materials   Wafer Fab Process	Packing/Shipping/Labeling  Notification Details  Description of Change:		Wafer Fab Materials				
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http://www.ti.com/product/TPS61500		L					
	http://www.ti.com/product/TPS61500						
Reason for Change:	Reason for Change:						
To accurately reflect device characteristics.	To accurately reflect device characteristics.						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):	Anticipated impact on Fit, Form, Function, Quality or Reliab	ility	(positive / negative):				
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.		nt on	y. There are no changes				
Changes to product identification resulting from this PCN:							
None.							
Product Affected:	Product Affected:						
	TPS61500PWP TPS61500PWPR						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com